What is claimed is:

1	1.	A storage device comprising:	
2		a probe; and	
3		a substrate comprising a storage medium and heating elements,	
4		the heating elements adapted to heat respective regions of the storage medium	
5	to form perturbations in the respective regions of the storage medium,		
6		the probe adapted to detect the perturbations.	
1	2.	The storage device of claim 1, wherein the perturbations comprise dents, and	
2	wherein the probe is adapted to form dents during write operations in regions of the storage		
3	medium that have been heated by respective heating elements.		
1	3.	The storage device of claim 2, wherein the storage medium has plural storage	
2	cells made up of the respective regions of the storage medium, the heating elements being		
3	associated w	rith respective storage cells.	
1	4.	The storage device of claim 3, further comprising select lines to select one or	
2	more of the heating elements,		
3		the select lines to activate at least one of the heating elements to heat a region	
4	of the storage medium corresponding to one of the storage cells to perform one of writing and		
5	erasing.		
1	5.	The storage device of claim 4, wherein the select lines are provided in the	
2	substrate.		
1	6.	The storage device of claim 5, wherein the substrate further comprises a first	
2	layer containing a first set of select lines, and a second layer containing a second set of select		
3	lines.		

7. The storage device of claim 3, wherein the heating elements are adapted to 1 heat respective storage cells to erase data stored by the storage cells. 2 The storage device of claim 1, wherein the substrate comprises a layer making 1 8. up the storage medium, the layer between the probe and the heating elements. 2 The storage device of claim 8, wherein the layer is formed of a material 9. 1 2. containing polymer. The storage device of claim 8, wherein a selected one of the heating elements 10. 1 is adapted to melt a region of the layer to enable the probe to form a dent in the melted 2 3 region. The storage device of claim 1, wherein the heating elements comprise resistive 1 11. 2 elements. The storage device of claim 1, wherein the storage medium has plural storage 12. 1 cells made up of respective regions of the storage medium, wherein each of the heating 2 elements is adapted to heat a respective group of plural storage cells. 3 The storage device of claim 1, wherein the heating elements are adapted to 13. 1 deactivate to cool the respective regions of the storage medium, wherein a rate of cooling of 2 the respective regions of the storage medium affects the crystallinity of the respective 3 regions. 4 The storage device of claim 13, wherein deactivation of a first heating element 1 14. 2 to cool a first region of the storage medium at a first rate causes the first region to have an amorphous structure, and wherein deactivation of a second heating element to cool a second 3 region of the storage medium at a second, slower rate causes the second region to have a 4 5 crystalline structure.

1	15.	The storage device of claim 14, wherein the probe is adapted to detect the		
2	amorphous structure of the first region and the crystalline structure of the second region			
3	based on detected resistances associated with the first and second regions, wherein the			
4	crystalline structure has a lower resistance then the amorphous structure.			
1	16.	The storage device of claim 1, wherein the perturbations comprise bumps		
2	formed above	a surface of the storage medium, the bumps caused by heating of respective		
3	heating elements.			
1 1	17.	A system comprising:		
2		a processor; and		
3		a storage device comprising:		
4		a probe, and		
5		a substrate comprising a storage medium and heating elements, the		
6	storage medium having plural storage cells,			
7		the heating elements adapted to heat respective storage cells for		
8	programming the storage cells,			
9		the probe adapted to read storage cells.		
1	18.	The system of claim 17, wherein the probe is adapted to be scanned across a		
2	surface of the	storage medium to read the storage cells.		
1	19.	The system of claim 18, wherein the storage device further comprises an		
2	actuator to move the substrate to cause scanning of the probe across the surface of the storag			
3	medium.	•		
1	20.	The system of claim 19, further comprising a probe substrate on which the		
2	probe is formed, the probe substrate further comprising additional probes to read the storage			
3	cells.			

l	21.	The system of claim 17, wherein heating by the heating elements causes		
2	perturbations to be formed in storage cells that are heated,			
3		wherein the probe is adapted to detect the perturbations to determine a data		
4	state.			
1	22.	The system of claim 21, wherein the probe is adapted to form a dent in a		
2	storage cell that has been heated by a corresponding heating element.			
1	23.	The system of claim 22, wherein the heating element is adapted to melt a		
2	region of the	storage medium corresponding to a storage cell to enable the probe to imprint a		
3	dent into the melted region.			
1	24.	The system of claim 17, wherein the heating elements comprise resistive		
2	elements.			
1	25.	The system of claim 24, wherein the storage device further comprises select		
2	lines to activate the resistive elements, and			
3		peripheral circuitry to activate the select lines.		
4	26	The section of claim 25. Southern wherein the color lines comprise electrically		
1	26.	The system of claim 25, further wherein the select lines comprise electrically		
2	conductive t	races in the substrate.		
1	27.	The system of claim 17, wherein the probe has a tip to interact with a heated		
2	region of the	e storage medium to form a respective perturbation during a write operation.		
1	28.	The system of claim 17, wherein the heating elements are adapted to heat		
2	respective st	orage cells to erase the storage cells.		
1	29.	The system of claim 19, wherein the probe comprises a nanotechnology probe.		

storage medium.

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1	30.	A method of storing data in a storage device, comprising:			
2		activating heating elements provided in a substrate to heat respective regions			
3	of a storage medium that is formed in the substrate;				
4		forming perturbations in regions of the storage medium by heating the selected			
5	regions with respective heating elements; and				
6		detecting the perturbations with a probe.			
1	31.	The method of claim 30, wherein activating the heating elements comprises			
2	activating resistive elements.				
1	32.	The method of claim 31, wherein activating the resistive elements comprises			
2	causing elect	trical current to conduct through the resistive elements.			
1	33.	The method of claim 29, wherein forming the perturbations comprises forming			
2	dents.				
1	34.	The method of claim 29, wherein forming the perturbations comprises forming			
2	bumps.				
1	35.	The method of claim 39, wherein forming the perturbations comprises forming			
2	at least one of an amorphous structure and a crystalline structure in a selected region of the				